

STARPOWER

SEMICONDUCTOR

IGBT

GD40TLQ120F1S

1200V/40A 3-level in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as solar power.

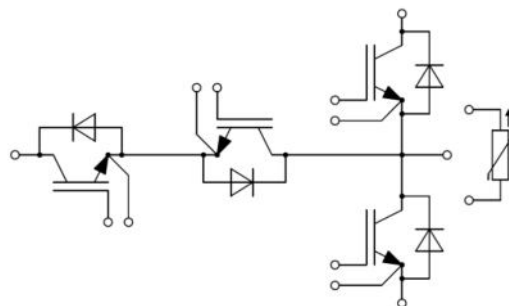
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- Low switching loss
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- Maximum junction temperature 175°C
- Fast & soft reverse recovery anti-parallel FWD
- Isolated heatsink using DBC technology

Typical Applications

- Solar power
- UPS
- 3-level-application

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**T1,T2 IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=100^{\circ}\text{C}$	66 40	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	80	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	244	W

D1,D2 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	25	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	50	A

T3,T4 IGBT

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$ @ $T_C=85^{\circ}\text{C}$	75 50	A
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	100	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	198	W

D3,D4 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	650	V
I_F	Diode Continuous Forward Current	30	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	60	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V

T1,T2 IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=40\text{A}, V_{GE}=15\text{V}, T_j=25^{\circ}\text{C}$		1.90	2.35	V
		$I_C=40\text{A}, V_{GE}=15\text{V}, T_j=125^{\circ}\text{C}$		2.20		
		$I_C=40\text{A}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}$		2.30		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1.6\text{mA}, V_{CE}=V_{GE}, T_j=25^{\circ}\text{C}$	5.6	6.2	6.8	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^{\circ}\text{C}$			400	nA
R_{Gint}	Internal Gate Resistance			TBD		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		TBD		nF
C_{res}	Reverse Transfer Capacitance			TBD		nF
Q_G	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		TBD		μC
$t_{d(on)}$	Turn-On Delay Time	TBD		TBD		ns
t_r	Rise Time			TBD		ns
$t_{d(off)}$	Turn-Off Delay Time			TBD		ns
t_f	Fall Time			TBD		ns
E_{on}	Turn-On Switching Loss			TBD		mJ
E_{off}	Turn-Off Switching Loss			TBD		mJ
$t_{d(on)}$	Turn-On Delay Time	TBD		TBD		ns
t_r	Rise Time			TBD		ns
$t_{d(off)}$	Turn-Off Delay Time			TBD		ns
t_f	Fall Time			TBD		ns
E_{on}	Turn-On Switching Loss			TBD		mJ
E_{off}	Turn-Off Switching Loss			TBD		mJ
$t_{d(on)}$	Turn-On Delay Time	TBD		TBD		ns
t_r	Rise Time			TBD		ns
$t_{d(off)}$	Turn-Off Delay Time			TBD		ns
t_f	Fall Time			TBD		ns
E_{on}	Turn-On Switching Loss			TBD		mJ
E_{off}	Turn-Off Switching Loss			TBD		mJ
I_{SC}	SC Data	TBD		TBD		A

D1,D2 Diode Characteristics $T_c=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=25\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.85	2.30	V
		$I_F=25\text{A}, V_{GE}=0\text{V}, T_j=125^{\circ}\text{C}$		1.90		
		$I_F=25\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.95		
Q_r	Recovered Charge	TBD		TBD		μC
I_{RM}	Peak Reverse Recovery Current			TBD		A
E_{rec}	Reverse Recovery Energy			TBD		mJ
Q_r	Recovered Charge	TBD		TBD		μC
I_{RM}	Peak Reverse Recovery Current			TBD		A
E_{rec}	Reverse Recovery Energy			TBD		mJ
Q_r	Recovered Charge	TBD		TBD		μC
I_{RM}	Peak Reverse Recovery Current			TBD		A
E_{rec}	Reverse Recovery Energy			TBD		mJ

T3,T4 IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=50\text{A}, V_{GE}=15\text{V}, T_j=25^{\circ}\text{C}$		1.45	1.90	V
		$I_C=50\text{A}, V_{GE}=15\text{V}, T_j=125^{\circ}\text{C}$		1.60		
		$I_C=50\text{A}, V_{GE}=15\text{V}, T_j=150^{\circ}\text{C}$		1.70		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=0.80\text{mA}, V_{CE}=V_{GE}, T_j=25^{\circ}\text{C}$	5.1	5.8	6.4	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^{\circ}\text{C}$			400	nA
R_{Gint}	Internal Gate Resistance			TBD		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		TBD		nF
C_{res}	Reverse Transfer Capacitance			TBD		nF
Q_G	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		TBD		μC
$t_{d(on)}$	Turn-On Delay Time	TBD		TBD		ns
t_r	Rise Time			TBD		ns
$t_{d(off)}$	Turn-Off Delay Time			TBD		ns
t_f	Fall Time			TBD		ns
E_{on}	Turn-On Switching Loss			TBD		mJ
E_{off}	Turn-Off Switching Loss			TBD		mJ
$t_{d(on)}$	Turn-On Delay Time	TBD		TBD		ns
t_r	Rise Time			TBD		ns
$t_{d(off)}$	Turn-Off Delay Time			TBD		ns
t_f	Fall Time			TBD		ns
E_{on}	Turn-On Switching Loss			TBD		mJ
E_{off}	Turn-Off Switching Loss			TBD		mJ
$t_{d(on)}$	Turn-On Delay Time	TBD		TBD		ns
t_r	Rise Time			TBD		ns
$t_{d(off)}$	Turn-Off Delay Time			TBD		ns
t_f	Fall Time			TBD		ns
E_{on}	Turn-On Switching Loss			TBD		mJ
E_{off}	Turn-Off Switching Loss			TBD		mJ
I_{SC}	SC Data	TBD		TBD		A

D3,D4 Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=30\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.60	2.05	V
		$I_F=30\text{A}, V_{GE}=0\text{V}, T_j=125^{\circ}\text{C}$		1.55		
		$I_F=30\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.50		
Q_r	Recovered Charge	TBD		TBD		μC
I_{RM}	Peak Reverse Recovery Current			TBD		A
E_{rec}	Reverse Recovery Energy			TBD		mJ
Q_r	Recovered Charge	TBD		TBD		μC
I_{RM}	Peak Reverse Recovery Current			TBD		A
E_{rec}	Reverse Recovery Energy			TBD		mJ
Q_r	Recovered Charge	TBD		TBD		μC
I_{RM}	Peak Reverse Recovery Current			TBD		A
E_{rec}	Reverse Recovery Energy			TBD		mJ

NTC Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			22.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_C=100^{\circ}\text{C}, R_{100}=1486.1\Omega$	-5		5	%
P_{25}	Power Dissipation				200	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		4000		K

Module Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Junction-to-Case (per T1,T2 IGBT)		0.558	0.614	K/W
	Junction-to-Case (per D1,D2 Diode)		1.095	1.204	
	Junction-to-Case (per T3,T4 IGBT)		0.685	0.754	
	Junction-to-Case (per D3,D4 Diode)		1.655	1.821	
R_{thCH}	Case-to-Heatsink (per T1,T2 IGBT)		0.186		K/W
	Case-to-Heatsink (per D1,D2 Diode)		0.365		
	Case-to-Heatsink (per T3,T4 IGBT)		0.229		
	Case-to-Heatsink (per D3,D4 Diode)		0.553		
	Case-to-Heatsink (per Module)		0.035		
M	Mounting Torque, Screw M4	2.0		2.2	N.m
G	Weight of Module		26		g

Terms and Conditions of Usage

The data contained in this product datasheet is exclusively intended for technically trained staff. you and your technical departments will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to such application.

This product data sheet is describing the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively pursuant the terms and conditions of the supply agreement. There will be no guarantee of any kind for the product and its characteristics.

Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you (see www.powersemi.cc), For those that are specifically interested we may provide application notes.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the Product in aviation applications, in health or live endangering or life support applications, please notify.

If and to the extent necessary, please forward equivalent notices to your customers.
Changes of this product data sheet are reserved.